

BAF-708

No Clean Tacky Paste Flux



Product Description

BAF-708 is a no-clean assembly flux specially designed for ball-attach, BGA re-balling and BGA rework applications. BAF-708 can be transferred to the pad by pin-transfer or ball-dip process involving a rotating disc a doctor's blade for flux levelling or a drum fluxer. The operating-life is >16 hours without much change in viscosity. BAF-708 can also be dispensed for BGA or SMD rework. Post-soldered residue is low and benign. If desired, residue can be removed with standard cleaners and megasonic energy.

BAF-708 has been optimised to have an unbeatable list of benefits, some are:

- Mild flux chemistry – no-clean flux design.
- Zero Halogen (ROLO) flux system - no corrosion.
- Trouble-free dispensing and dipping – no tailing and no choking till syringe is empty.
- High tack force – secures component in place prior to reflow.
- Fast wetting – smooth solder joint.
- Cosmetically clean appearance – ultra-low residue.
- Negligible interfacial void – high joint reliability.
- No-clean formulation – if desired, residue can be removed with standard cleaners with ultrasonic energy.

Application

BAF-708 is great for general lead free and leaded applications and also rework applications of various electronic devices. It is ideally suited for applications such as pin transfer, ball dip process and stencil printing process.

For a 0.2 x 0.2mm pad, ca 100µl of flux may be acceptable for good soldering. The chip should be pressed into the flux and make contact with the pad. These are intended for minimal risk of chip movement during reflow. For dipping or pin transfer, flux should cover 50-70% of the ball height.

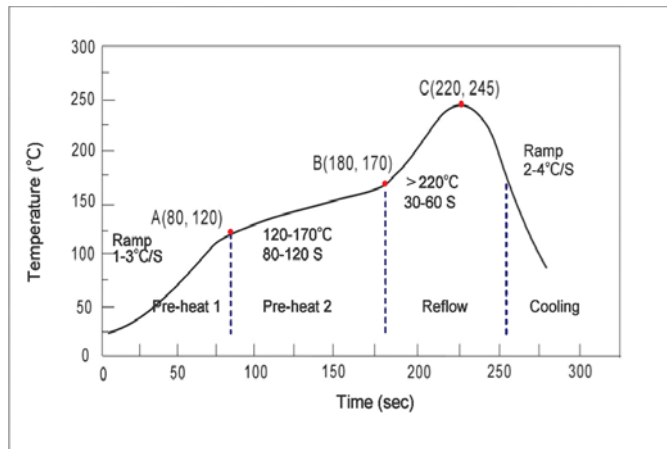
Specification (Preliminary)

Item	Result
Appearance	white color paste
Viscosity	16 +/- 2 Pa.s
Density	0.85 g/cm ³
Halide Content <small>JIS Z 3197 8.1.4.2.1</small>	No Detected
Copper Mirror Test <small>IPC-TM-650 2.3.32 JIS Z 3197 8.4.2</small>	Classified as "L", Pass
Copper Corrosion Test <small>IPC-TM-650 2.6.15 JIS Z 3197 8.4.1</small>	Pass
Flux Activity Classification <small>IPC J-STD-004</small>	ROLO
Surface Insulation Resistance <small>(85°C, 85%RH, 168hrs) IPC-TM-650 2.6.3.3</small>	> 1 x 10 ⁸ Ω, Pass
Electromigration <small>(85°C, 88.5%RH, 596hrs) IPC-TM-650 2.6.14.1</small>	Pass

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Recommended Reflow Profile

BAF-708 can be used to reflow SAC305 solder spheres in nitrogen (N₂) with the following profile:



Residue Removal

Post-soldered residue of BAF-708 can be removed by most commercial solvent.

Storage, Handling and Shelf Life

Paste flux has to be thawed to room temperature (~25°C) prior using to avoid condensation. Paste flux left on the stencil should not be put back into the container together with the unused paste flux. It is preferable not to re-use paste flux left on the stencil after printing. BAF-708 can be stored at 20-25°C and used within 6 months.

Health and Safety

Do not handle the paste flux with your bare hand. Use proper tool when handling the paste flux. If the paste flux touches the skin, wash thoroughly with soap and water. For more information, please refer to Material Safety Data Sheet. paste touches the skin, wash thoroughly with soap and water. For more information, please refer to Material Safety Data Sheet.

Packaging

BAF-708 paste flux is available in 10gm and 30gm luer-lok syringes. For other packaging requirements, please contact Asahi sales department.

DISCLAIMER OF LIABILITY

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